1. PURPOSE

1.1. The purpose of this document is to define the minimum quality and reliability criteria that our suppliers must comply with.

1.2. Diodes Incorporated (Diodes) wants to ensure that all our foundry supplier are aware of our quality and reliability requirements so that the products received are of the highest quality, free from any defects including material and workmanship.

1.3. Supplier shall assume responsibility and liability for all costs associated with recovery of defective material.

1.4. All suppliers will be objectively measured against our quality policies as they pertain to suppliers. A system of feedback and an opportunity for improvement will be provided on a case-by-case basis.

1.5. Partnerships will be maintained with suppliers that are committed to meet or exceed Diodes’ quality and reliability requirements. Suppliers that continually exceed the expectations as identified in this document may be presented with an opportunity for increased business and will obtain a preferred supplier status.

2. SCOPE

2.1. The procedures and the quality requirements defined herein shall apply to all Diodes’ wafer fab (foundry) suppliers and its subsidiaries and affiliates worldwide. It shall apply also to foundry planning to supply product to Diodes.

2.2. All communications must, at a minimum, have accurate English translations.

2.3. It is the responsibility of each supplier to ensure that these requirements are met.

3. DEFINITIONS

3.1. 8D – Eight Discipline

3.2. BOM – Bill of Materials

3.3. CoC – Certificate of Conformance

3.4. ECN – Engineering Change Notification

3.5. FMEA – Failure Mode Effects Analysis

3.6. GP – Sony Green Partner

3.7. IPQC – In-line Process Quality Control

3.8. IQC – Incoming Quality Control

3.9. MDS – Material Data Sheet

3.10. OQC – Outgoing Quality Control
QUALITY PROCEDURE

CORPORATE SUPPLIER QUALITY SPECIFICATION
FOR WAFER FOUNDRIES

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3.11. ORT – Ongoing Reliability Testing
3.12. PCN – Process Change Notification
3.13. PF – Premium Freight
3.14. PPAP – Production Part Approval Process
3.15. QC – Quality Control
3.16. QRA – Quality and Reliability Assurance
3.17. RMA – Return Material Acceptance
3.19. SCAR – Supplier Corrective Action Request
3.20. SGS – Société Générale de Surveillance
3.21. SPC – Statistical Process Control
3.22. Cp - Process Capability
3.23. Cpk – Process Capability Index
3.24. Supplier – Wafer Foundry (Manufacturer)
3.25. Conflict Minerals – Gold, Tin, Tantalum and Tungsten, sold to finance conflict in the Democratic Republic of Congo and adjoining countries
3.26. DRC – Democratic Republic of Congo and adjoining countries
3.27. WRO – Wafer Release Order

4. REFERENCES

4.1. DIC-021 – Quality Record Control, Retention & Archiving
4.2. AD30-2-003 Supplier Select and Management Procedure
4.3. AD30-3-003 Supplier Evaluation Procedure
4.4. DIC-906 Non-Disclosure Agreement

5. RESPONSIBILITIES:
   5.1. Diodes Supplier Quality Engineering
   
   5.1.1. Diodes SQE is responsible for the maintenance of this document.
5.1.2. The Diodes SQE with Outsourcing and applicable Business Unit will review and approve the contract and Quality related terms and conditions required in this document with wafer supplier.

5.1.3. The Diodes SQE is responsible for certifying and qualifying suppliers in accordance with AD30-2-003 and AD30-3-003.

5.1.4. The Diodes SQE shall review and approve all related reports and requested deviations to this specification.

5.1.5. Diodes will document any transfer of propriety knowledge to the supplier in accordance with DIC-906 Non-Disclosure Agreement.

5.2. Outsourcing and Business Unit

5.2.1. Outsourcing and applicable business unit are responsible for ensuring this document is included with any supplier contract agreement.

5.2.2. Outsourcing and applicable business unit shall notify the responsible Diodes SQE of any deviations from this document reported by supplier.

5.3. Wafer Supplier

5.3.1. It is the responsibility of the wafer fabrication supplier to comply with the requirements listed herein under the terms and conditions specified in the applicable contract agreement, purchase order, or WRO.

5.3.1.1. Any deviation out this specification shall be agreed and documented by both Diodes and Supplier.

5.3.2. Suppliers will provide the data requirements listed in this document directly to the responsible SQE.

5.3.3. Suppliers will address all quality related issues or corrective action plans pertaining to this document to the responsible SQE.

5.3.4. Suppliers will work with Business Unit or MQE (Manufacturing Quality Engineering) on all process related issues.

5.3.5. Suppliers will contact Outsourcing on all scheduling related issues.

6. SPECIFICATION REVIEW

6.1. Qualified suppliers are expected to meet or exceed all requirements as specified by Diodes.

6.2. For new suppliers, a baseline review in accordance with the specification outlined in this document will be conducted. Any non-compliance or deviations from Diodes’ internal specifications must be resolved and documented. This may require modifications or amendments to the supplier’s specifications.
7. **CERTIFICATES**

7.1. All of Diodes’ qualified suppliers must be ISO 9001 certified (or equivalent) and highly recommend being ISO 14001 certified. If end products are intended for the automotive market, an IATF16949 certification is required.

7.2. All suppliers shall have their quality systems audited by an un-biased and registered third party audit agency.

7.3. Upon request, all suppliers should be able to present Diodes with a copy of their registration certificate and results, i.e. audit reports.

7.4. For those seeking to become a qualified Diodes supplier and have failed Diodes’ qualification requirements must provide feedback to Diodes with an improvement plan within 7 working days or the negotiated schedule agreed upon by Diodes and the supplier. Supplier cannot apply for re-qualification during this period.

8. **AUDITS**

8.1. Prior to becoming a Diodes’ supplier, the requestor must first complete an assessment and/or audit as requested by the group or person managing the supplier qualification.

8.1.1. Supplier is required to complete AD30-2-003-02 Supplier survey report, AD30-2-003-04 Quality System & Environment Assessment Summary Report and AD30-2-003-09 Supplier Process assessment Summary Report for Diodes review.

8.1.2. After review of the completed forms by Diodes, Diodes will determine if a site audit is required.

8.2. Diodes’ suppliers shall be audited upon request. Advance notification of an up-coming audit will be provided along with an audit plan, scope, and schedule.

8.3. All audits will be conducted in compliance with ISO 9001 or IATF16949 for automotive. Diodes may also audit per VDA 6.3.

8.4. Any non-conformance that may materialize in the completed Quality System & Environment Assessment Summary Report and Supplier Process assessment Summary Report by the supplier or audit will require corrective/preventive actions.

9. **FOUNDRY SOURCING**

9.1. Diodes will provide the scope for the project, product, and/or services requested.

9.2. Diodes will provide the specifications for the project, product, and/or services requested. Supplier must comply with the specifications fully.

9.3. Diodes will provide suppliers with a qualification plan, which suppliers must execute, and pass in order to meet Diodes’ quality and reliability requirements.

9.4. Diodes will provide each supplier with an official document stating that the supplier is a qualified Diodes supplier.
9.5. Diodes will document that the supplier maintains the effectiveness of all its communication processes, quality systems, and meets all Diodes’ requirements.

9.6. It is the responsibility of the supplier to ensure that any changes initiated by the supplier must comply with Diodes quality, reliability, and change management requirements.

9.7. Diodes will document any transfer of propriety knowledge to the supplier in accordance with DIC-906 Non-Disclosure Agreement.

9.8. Diodes will provide the supplier with all technical, traceability, packing, and shipping requirements

10. PROCESS INFORMATION and REWORK CRITERIA:

10.1. The following information shall be provided to Diodes Business Unit by the wafer supplier for each process. (Normally provided prior to design activity)

10.1.1. Process flow chart with monitor points and monitor frequency.

10.1.2. Device cross-section, step coverage, junctions, etc.

10.1.3. All final layers thickness, with process tolerances.

10.1.4. Parametric statistics.

10.2. Non-mask operations related rework is not allowed on any Diodes product.

10.3. Mask operations rework allowed only one time.

11. PARAMETRIC TEST:

11.1. Parametric specification limits will be mutually agreed upon between DIODES and the supplier for each process. (Suggested parameters are referenced in Table 1.)

11.2. All wafers in each wafer lot will be tested. The PCM data shall be readily available to Diodes when requested. If requested B2B file transfer shall be supported.

11.3. A minimum of three (3) and a maximum of five (5) PCM sites from each wafer shall be electrically tested to parametric specification limits.

11.4. The wafer is acceptable if at least two (2) out of three (3) or four (4) out of five (5) PCM sites pass each of the wafer acceptance parameters.

11.5. Failing wafers shall be removed from the lot and disposition.

11.6. Disposition of failed wafers:

11.6.1. Rejected wafers will be evaluated by the supplier and results provided to Diodes upon request.

11.6.2. If >4 wafers was cumulatively scrapped in a fab lot at any time, the suppliers must notify SQE and provide details of scrap and corrective action.

12. WAFER SORT (CP, Circuit Probe)- Only when specifically requested by Diodes

12.1. For material sorted by the wafer fab supplier:
12.1.1. Diodes and the supplier will establish mutually agreed upon Standard Yields on the basis of wafers which have passed parametric test and have no identifiable processing problem.

12.1.2. Wafers with less than 85% of Standard Yield will be rejected by the supplier. Rejected wafers will be evaluated by the supplier and results provided to Diodes upon request.

12.2. For material shipped to DIODES unsorted:

12.2.1. The supplier and DIODES will agree on a standard yield for each product.

12.2.2. The lot may be sorted by DIODES or an approved DIODES vendor, when required.

12.2.3. If the lot averages >85% of the preliminary standard yield, the lot is acceptable.

12.2.3.1. Wafers yielding less than 75% of the standard yield will be rejected by the supplier.

12.2.3.2. If the cause of low yield is not due to test issues, the rejected wafers may be returned the supplier for analysis. A supplier corrective action request (SCAR) may be issued to supplier.

12.2.3.3. The returned wafers will be analyzed by the supplier and the findings will be reported back to DIODES SQE as requested on the SCAR.

12.2.4. If the lot averages less than 85% of the preliminary standard yield, and the cause is not due to test issues, the following will be done:

12.2.5. The lowest yielding wafers will be removed from the lot until the yield of the remaining wafers is 85% of standard or more.

12.2.6. The remaining wafers, yielding 85% of standard or more, are acceptable.

12.2.7. The removed wafers will be rejected and returned to supplier for credit or replacement.

12.2.8. The returned wafers will be analyzed by the supplier and the findings will be reported back to DIODES SQE within 30 days.

12.3. FUNCTIONAL WAFER PROBE FLOW

12.3.1. Probe test programs, including revisions to existing programs, must be reviewed and formally approved by the responsible Diodes product engineering organization prior to being released to production.

12.3.2. Probe yield parameters if different from above will be discussed, agreed upon with Diodes, and set on a case-by-case product basis.

12.3.3. Products included in the MPE (Maverick Product Elimination) program shall be supported by the suppliers. Diodes will notify the suppliers the list of products under MPE. Maverick lot limits calculation will be per Diodes requirement or need to be discussed and agreed upon with Diodes.

12.3.4.

13. VISUAL INSPECTION CRITERIA: All wafers received by Diodes are subject to the visual requirements set forth below. Wafer suppliers are expected to ensure that product is of equal quality or better when wafers are shipped to the assembly supplier rather than directly to Diodes.

13.1. All wafers received by Diodes may be visually inspected. If wafers are sort probed prior to visual inspection, the supplier is not responsible for rejects due to probing damage.
13.2. Inspection criteria are per the requirements as stated below. The lot will be subject to an inspection plan LTPD of 20%. If any inspected wafer has more than 20% of the sites fail, the wafer fails and the lot is considered to have failed.

13.2.1. Inspection plan:
   13.2.1.1. Inspect 5 die on each of 5 wafers.
   13.2.1.2. Accept the lot with 2 defects, fail on 3 defects.
   13.2.1.3. If 2 or more defects occur on one wafer (>20%), the wafer fails, and the lot has failed.

13.2.2. For incoming wafers, visual inspection will be done (at Diodes discretion) prior to probing to identify potential problems such as scratches.
   13.2.2.1. Unless there is a severe problem, such as a suspected reliability problem, a lot will continue through probing followed by the usual post-probe visual inspection.

13.2.3. Lots that have failed visual are to be reviewed and disposition by MRB.
   13.2.3.1. Wafers and lots that have failed may be returned to supplier for credit or replacement.
   13.2.3.2. Feedback will be provided to the supplier on valid failures.

13.2.4. The visual criteria shall be per MIL-STD-883, Method 2010, Test Condition B (latest revision in effect) and below. (Criteria pertaining to assembly issues are excluded.)

13.3. Wafers must be <1 month for Ag BM, <6 months for Au BM when they are shipped to Diodes.

14. REPORTING REQUIREMENTS:

14.1. Standard Data Reporting: The following shall be provided on a monthly basis:

14.1.1. SPC data (Cp/Cpk) for key process parameters. (SPC is the primary tool for monitoring the manufacturing process to minimize variability.)
   14.1.1.1. Table 1 contains examples of key process parameters that may be reported.
   14.1.1.2. Wafer Level Reliability monitor reports, which in addition to “standard” testing that may be performed by the supplier, shall include Electro migration and Vt stability monitors.
   14.1.1.3. Reporting of additional parameters may be required as deemed appropriate for individual processes and/or facilities.

14.1.2. Data required for each critical process parameter:
   14.1.2.2. Number of samples.
   14.1.2.3. Average reading and sigma of samples.
   14.1.2.4. Average Cp and Cpk, and Minimum Cpk.

14.1.3. The supplier shall provide an improvement plan for processes with Cpk’s of less than 1.67.

14.1.4. Processes with Cpk’s less than 1.33 shall have corrective action taken.

14.1.5. Processes less than 1.0 shall have the affected process shut down until corrective action has been determined and implemented.
14.1.6. The supplier shall provide the Pareto of failure modes

14.1.7. The supplier shall provide the Number of quality incidents related to Diodes

14.1.8. Special Data Requests: Supplier shall provide the following data/information to Diodes, when requested. (Equivalent, mutually agreed upon data may be acceptable.)

14.1.8.1. Summary of PCM data by lot, including individual site data if requested.
14.1.8.2. When applicable, wafer sort yield data by wafer, including test summaries.
14.1.8.3. Visual inspection summary by wafer and lot.
14.1.8.4. Notice of any non-compliance and/or discrepancy report, including engineering disposition and justification.
14.1.8.5. Metallization step coverage photos of worst case step coverage.
14.1.8.7. Cycle time
14.1.8.8. Short and long range goals/plans for Cp and Cpk in order to achieve 6 sigma and the progress to date.
14.1.8.9. Process improvement plans, including yield enhancement, and progress to date.

15. FOUNDRY QUALIFICATION

15.1. Diodes QRA will define all foundry qualifications.

15.2. Diodes QRA will grant approval of qualification upon review of qualification data.

15.3. All qualification must comply with the qualification specifications provided by Diodes and must follow Diodes’ change management procedures including issuing PCNs, providing a schedule of shipments of qualified material, submitting all quality, reliability, and other supporting data pertaining to the qualification being conducted. Supporting data may include, but not limited to:

15.3.1. BOM
15.3.2. Process Control Plans
15.3.3. FMEAs
15.3.4. Statistical Process Control (SPC)
15.3.5. Material and Functional Tests
15.3.6. Equipment List
15.3.7. Equipment Calibration Records
15.3.8. Process Flows
15.3.9. SGS/MDS data
15.3.10. EICC/GeSI Conflict Minerals report
16. QUALITY ISSUES AND INCIDENTS

16.1. All supplier quality issues and incidents will need to be addresses through a Corrective Action Request (CAR). All CARs must be in an 8-D format.

16.2. Diodes will provide the supplier with customer's problem description and all relevant information pertaining to a particular claim.

16.3. Diode expects all suppliers to provide a preliminary CAR within 24 hours of receipt of the samples.

16.4. Diode expects all suppliers to provide a final CAR within 7 business days of receipt of the samples with evidence of closure.

16.5. Diodes will also provide specific requests for FA (i.e. specific tests to be performed or FA techniques to be applied, if applicable, especially for automotive products)

16.6. OCAP Management:

16.6.1. A dedicated OCAP (out of control action plan) flow should be included in the quality management system.

16.6.2. The trigger conditions/impacted range/root cause and corrections closed loop should be included in OCAP.

16.6.3. Supplier should provide their OCAP trigger conditions to Diodes

17. CONTINUOUS IMPROVEMENT ACTIVITIES

17.1. Supplier will apply lessons learned and corrective actions identified during a quality incident in order to improve controls to prevent such quality incidents from reoccurring.

17.2. Supplier will implement these new controls into other products manufactured for Diodes.

17.3. Supplier will verify the effectiveness of the new controls.

17.4. Supplier's control plans and FMEAs should be updated as needed.

17.5. Supplier will document its continuous improvement efforts and provide updates to Diodes for review.
18. **SUPPLIER IN-COMING/OUT-GOING QUALITY CONTROL**

18.1. Supplier will provide their IQC/OQC specifications for review by Diodes QRA against Diodes internal specifications and requirements. Any deviations will be reported back to the suppliers who will have to align their internal specifications with Diodes’ requirements.

18.2. Supplier is responsible for self-inspection of out-going wafer quality according to the process outlined in the Control Plan.

18.3. Supplier’s IPQC inspector should inspect each control point with the frequency specified in the inspection procedure, document pass or fail criteria and results in the traveler, and complete relevant inspection records.

18.4. Only material that has passed IPQC can be transferred to the next station. Any material that does not meet this criterion must be segregated and a product control procedure must be implemented to address the issue.

18.5. Diodes may request PPM results for each process.

19. **ON-GOING RELIABILITY**

19.1. Qualified suppliers will perform on-going reliability testing (ORT). The supplier will provide an annual plan for ORT that should cover each product family. Data has to be provided to Diodes on a quarterly basis.

19.2. If there are any failures, the supplier will immediately quarantine the affected lot, notify Diodes of the incident, and initiate failure analysis.

19.3. Once the containment actions, root cause, and corrective actions have been identified, the supplier will work with Diodes to address proper disposition of the affected material. RMAs which may be issued will be based on whether the parts were affected at Diodes or in the field.

20. **SUPPLIER REPORT CARD AND ASSESSMENT**

20.1. Supplier’s performance will be reviewed and assessed on a quarterly basis based per Diodes’ internal procedures. Refer to AD30-3-003 Supplier Evaluation Procedure.

21. **CHANGE MANAGEMENT (ECN/PCN)**

21.1. Supplier will issue a Diodes - Supplier_Subcon PCN_ECRECN submission form (AD30-2-003-11) to Diodes SQE for planned changes as indicated in Section 18.3. Diodes SQE will review and submit to QDMS ECR for approve changes and Diodes QRA will determine if a customer notification of Diodes customers will be required via PCN.
21.2. With regards to any changes requested by Diodes, Supplier must provide Diodes with an acknowledgement of receipt of the change request. Additionally, Supplier must also provide Diodes with notification once the change has been implemented.

21.3. Supplier ECN/PCN minimum content:
   21.3.1. Reason for change
   21.3.2. Detailed description of change
   21.3.3. Implementation date of change
   21.3.4. Qualification sample wafers availability date
   21.3.5. Qualification report availability date
   21.3.6. Manufacturing discontinuance date
   21.3.7. Changes requiring notification:
      21.3.7.1. Location change or transfer of product line, machine, or equipment
      21.3.7.2. New, additional, or change in foundry and/or test location
      21.3.7.3. Addition of new equipment or manufacturing technique
      21.3.7.4. Change in manufacturing process
      21.3.7.5. Redesign of existing structures or the addition of new active components that changes the die size, the dimensions of active components, the spacing or the isolation
      21.3.7.6. Wafer diameter
      21.3.7.7. Metallization material/thickness
      21.3.7.8. Gate oxide material/process
      21.3.7.9. Passivation material/thickness
      21.3.7.10. Change in electrical testing
         21.3.7.10.1. Test elimination
         21.3.7.10.2. Electrical specification changes
         21.3.7.10.3. Change in AC specification
         21.3.7.10.4. Change in DC specification
      21.3.7.11. Change in suppliers’ suppliers
      21.3.7.12. Changes in Packing, Shipping, and Labeling
      21.3.7.13. Change in company’s name or ownership
22. **CODE OF CONDUCTS**
Diodes expects its direct suppliers
19.1 to comply, at a minimum, with applicable labor and environmental laws and regulations of the countries in which products are grown or produced, including laws against human trafficking, compulsory prison labor, child labor, slave labor or physical abuse of workers, and
19.2 to monitor their suppliers for compliance with the labor and environmental laws and regulations of the countries in which they have operations.

As such, Diodes expects its suppliers to implement a Code of Conduct that is modeled on the Electronic Industry Code of Conduct (EICC) and defines labor, health and safety, environmental, and business ethics standards, as well as a management system to assure continued compliance to this code.

23. **CONFLICT MINERALS**
23.1. Conflict Minerals originating from the DRC must not be included in materials or products supplied to Diodes or its subsidiaries.
23.2. Conflict Minerals must be sourced from certified conflict free smelters validated as compliant to the EICC Conflict Free Smelters (CFS) protocol, using the CFS Compliant Smelter List
23.3. Suppliers shall query their direct suppliers using the EICC/GeSI Conflict Minerals reporting template, following up with those suppliers that do not respond to the query.
23.4. Suppliers shall inform Diodes if their products contain Conflict Minerals using the EICC/GeSI Conflict Minerals reporting template, incorporating the replies from their suppliers. A revised report shall be submitted at least annually to Diodes' Environmental Compliance Coordinator via compliance@diodes.com.
23.5. Suppliers shall make their Conflict Minerals Policy publicly available and inform Diodes of its location.
23.6. Suppliers shall inform Diodes without delay about changes in products containing Conflict Minerals if they are known to be sourced from the DRC or adjoining countries. In that case the supplier shall take action to remedy the situation in a timely manner.
23.7. Suppliers shall disseminate requirements 25.1 - 25.7 to their suppliers.

24. **TRACEABILITY**
24.1. Supplier must meet Diodes traceability requirements as requested.
25. Data Retention

25.1. Diode requires all suppliers to retain all quality records. These records need to be readily retrievable and stored in a manner that will not deteriorate the data.

25.2. Refer to Diodes specification DIC-021 Quality Record Control, Retention & Archiving.

### TABLE 1:

**KEY PROCESS SPC PARAMETERS**

<table>
<thead>
<tr>
<th></th>
<th>Operation</th>
<th>Key Parameters</th>
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<tbody>
<tr>
<td>1.</td>
<td>Field Oxide</td>
<td>Oxide Thickness</td>
</tr>
<tr>
<td>2.</td>
<td>Diffusion</td>
<td>Linewidth (CD)</td>
</tr>
<tr>
<td>3.</td>
<td>Gate Oxide</td>
<td>Oxide Thickness</td>
</tr>
<tr>
<td>4.</td>
<td>Poly Deposition</td>
<td>Film Thickness</td>
</tr>
<tr>
<td>5.</td>
<td>Silicide Deposition Film Thickness</td>
<td>Film Thickness</td>
</tr>
<tr>
<td>6.</td>
<td>Phosphorus Diffusion (Poly)</td>
<td>Sheet Resistance</td>
</tr>
<tr>
<td>7.</td>
<td>Poly Etch</td>
<td>Linewidth (CD)</td>
</tr>
<tr>
<td>8.</td>
<td>Silicide Etch</td>
<td>Linewidth (CD)</td>
</tr>
<tr>
<td>9.</td>
<td>Glass Deposition</td>
<td>Dopant Concentrations (P and B)</td>
</tr>
<tr>
<td>10.</td>
<td>Glass Deposition</td>
<td>Film Thickness</td>
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<tr>
<td>11.</td>
<td>Contact Etch</td>
<td>Linewidth (CD)</td>
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<tr>
<td>12.</td>
<td>Metal 1 Deposition</td>
<td>Film Thickness</td>
</tr>
<tr>
<td>13.</td>
<td>Metal 1 Etch</td>
<td>Linewidth (CD)</td>
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<tr>
<td>14.</td>
<td>Intermetal Dielectric Deposition</td>
<td>Film Thickness</td>
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<tr>
<td>15.</td>
<td>Via Etch</td>
<td>Linewidth (CD)</td>
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<td>16.</td>
<td>Metal 2 Deposition</td>
<td>Film Thickness</td>
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<tr>
<td>17.</td>
<td>Metal 2 Etch</td>
<td>Linewidth (CD)</td>
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<td>18.</td>
<td>Nitride Deposition</td>
<td>Film thickness</td>
</tr>
<tr>
<td>19.</td>
<td>Nitride Deposition</td>
<td>Stress (Stress measurement, refractive index)</td>
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QUALITY PROCEDURE

CORPORATE SUPPLIER QUALITY SPECIFICATION FOR WAFER FOUNDRIES

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<table>
<thead>
<tr>
<th>Revision</th>
<th>Revision History</th>
<th>Request Date</th>
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</thead>
<tbody>
<tr>
<td>4</td>
<td>4 Remove QP references, add AD30 references; 7 Edit ISO requirement, change TS to IATF; 8 Add AD30 specs to audit, ISO update and TS to IATF; 14 Add PCM analysis report, remove QP; 15 Remove QP requirements; 17 Add AD30 requirement; 18 Change ECN/PCN to reference document, update responsibility; 22 Add data retention requirement.</td>
<td>3/26/2018</td>
</tr>
<tr>
<td>5</td>
<td>Added Responsibility clause, Process Information and rework criteria, Parametric test requirement, Wafer sort requirement, Visual inspection requirement, and Reporting requirements. Added Table 1: Key Process SPC parameters.</td>
<td>5/15/2018</td>
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